

Serial No.
Infineon Ref No. FIN5688CT/US
OC Ref No. I431.173.101

**DECLARATION FOR PATENT APPLICATION, POWER OF
ATTORNEY & DESIGNATION OF CORRESPONDENCE ADDRESS**

As below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**NON-LEADED SEMICONDUCTOR PACKAGE AND A METHOD TO ASSEMBLE THE
SAME**

the specification of which (check one)

X is attached hereto.

_____ was filed on 26 February 2004 as PCT International Application Number PCT/IB2004/000496, which entered the U.S. National Stage on August 26, 2006 under U.S. Application No. _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information known to me to be material to the patentability of this application in accordance with 37 CFR §1.56(a).

**PRIOR FOREIGN/PCT APPLICATION(S) FILED WITHIN 12 MONTHS (6 MONTHS FOR
DESIGN) PRIOR TO THIS APPLICATION AND ANY PRIORITY CLAIMS UNDER 35 U.S.C. §
119(a)-(d)**

I hereby claim foreign priority benefits under 35 USC § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
Number	Country	Day/Month/Year Filed	Yes	No
PCT/IB2004/000496	IB	26 February 2004	X	

CLAIM FOR BENEFIT OF PRIOR U.S. PROVISIONAL APPLICATION(S)
(35 U.S.C. § 119(e))

I hereby claim the benefit under Title 35, United States Code, § 119 (e) of any United States provisional application(s) listed below:

Provisional Application Number	Filing Date

CLAIM FOR BENEFIT OF EARLIER US/PCT APPLICATION(S)
UNDER 35 U.S.C. § 120

I hereby claim the benefits under 35 USC § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of 35 USC § 112, I acknowledge the duty to disclose material information as defined in 37 CFR § 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Appl. No.	Filing Date	Patented, Pending, Abandoned

Power of Attorney: As a named inventor, I hereby appoint the practitioners under Customer Number

45782

jointly, and each of them severally, my attorneys at law/patent agent(s), with full power of substitution, delegation and revocation, to prosecute this application and any continuations, divisions, reissues, and reexaminations thereof, to receive the patent(s), to transact all business in the United States Patent and Trademark Office connected therewith and to act on my behalf before the competent International Authorities in connection with any and all international applications filed.

Send correspondence to:

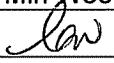
025281

Direct telephone calls to:

Steven E. Dicke

612-573-2002

I hereby declare that all statements made herein on my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both under 18 USC §1001 and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Full Name of First Inventor: Min Wee Low	
Inventor's Signature: 	Date: 16.10.06
Residence: Singapore, Singapore	
Citizenship: Singapore	
Mailing Address: Bld 625 Senja Road, #02-148, 670625 Singapore, Singapore	

Full Name of Second Inventor: Tian Siang Yip	
Inventor's Signature: 	Date: 16.10.06
Residence: Singapore, Singapore	
Citizenship: Singapore	
Mailing Address: 3 Flora Drive #6-12, 507010 Singapore, Singapore	